ABSTRACT

The present invention relates to a heat-medium supply apparatus for supplying a heat medium to a temperature control apparatus configured to regulate a temperature of a semiconductor manufacturing apparatus, such as an etching apparatus, a CVD apparatus, or a PVD apparatus. The heat-medium supply apparatus (3) includes a cooling device (7) configured to cool a first heat medium, a heating device (8) configured to heat a second heat medium, a cooling-medium delivery pipe (11) configured to deliver the cooled first heat medium to the temperature control apparatus (2), a heating-medium delivery pipe (12) configured to deliver the heated second heat medium to the temperature control apparatus (2), and an operation controller (35) configured to control an operation of the cooling device (7). The operation controller (35) is configured to, when a thermal load on the cooling device (7) exceeds a cooling-load threshold value, instruct the cooling device (7) to switch the operation of the cooling device (7) from a rated cooling operation to an overload cooling operation.

FIG. 1